

# HORUS440

Intel 4<sup>th</sup> XEON SP Rugged Server



## Features

- ◆ Intel® 4th XEON® SP Processor Sliver 4410T/Gold 6421N
- ◆ Intel® Data Center GPU Flex 170(32 Xe-cores, 16GB GDDR6)
- ◆ Nvidia RTX 6000 ADA Generation 48GB GDDR6 960GB/s 18176 CUDA® cores
- ◆ 128GB DDR-4 3200 RDIMM ECC
- ◆ 16-bit programmable GPIO
- ◆ 4 x U.2 NVMe PCIe Gen 4 (Up to 64TB)
- ◆ 1x M.2 NVMe (OS)
- ◆ I/O: 1xIPMI , 2x10G , 4x1G
- ◆ 1 x FHHL Slot Available
- ◆ DC 16V-72V (1000W)

### OPTIONAL

- ◆ 6x GMSL 2.0 inputs
- ◆ RAID PCIe Gen 4.0 Tri-Mode Support RAID 0, 0, 0, 1, 5, 6, 10, 50 and 60

# Specifications

## System

Processor	Intel® 4 <sup>th</sup> XEON SP Gold 6421N, 1.8GHz, 60MB, 185W, 32 cores/64 Threads Intel® 4 <sup>th</sup> XEON SP Silver 4410T, 2.7GHz, 26.25MB, 150W, 10 cores/20 Threads
Memory type	128GB DDR4-3200 RDIMM ECC
Graphic	Intel® Data Center GPU Flex 170(32 Xe-cores, 16GB GDDR6) Nvidia RTX 6000 ADA Generation 18176 CUDA cores 48GB GDDR6 960MB/s
TPM	Chipset: Infineon, Type: TPM 2.0
IPMI	ASPEED AST2500 IPMI 2.0
BIOS	AMI UEFI BIOS
USB	6 USB3.2 Gen1 ports: 4 rear Type-A, 2 via 19-pin header
Ethernet	2 x 10G Ethernet Ports 4 x 1G Ethernet Ports 1 x RJ45 Dedicated IPMI
Power Type	16V ~ 72V DC IN 1000W
Storage	4 x 2.5" Swappable SSD Tray support U.2 NVMe PCIe Gen4 x 4 up to 64TB (Data) 1 x M.2 NVMe (OS)
COM Port	1 x RS232
Operating Temperature	-20°C to +60°C
Dimension	440mm(W) x 400mm(D)x88mm(H)

## FRONT I/O

Power Button	1
SSD LED indicator	1
Swappable SSD Tray	4

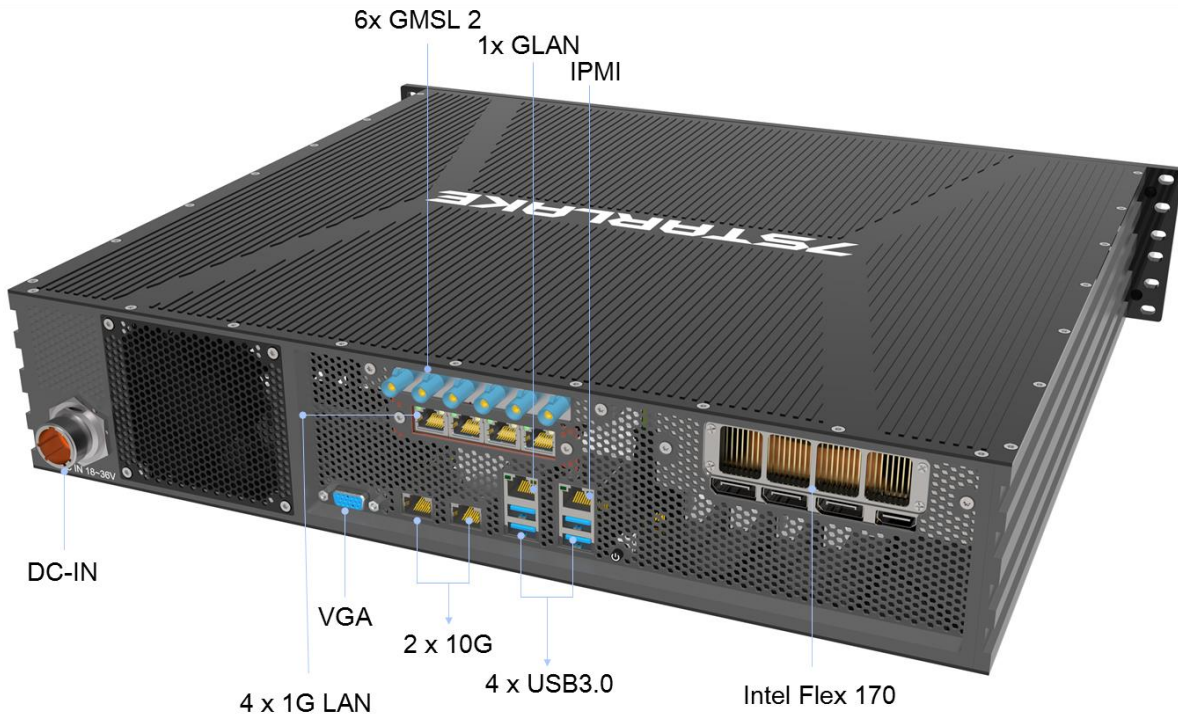
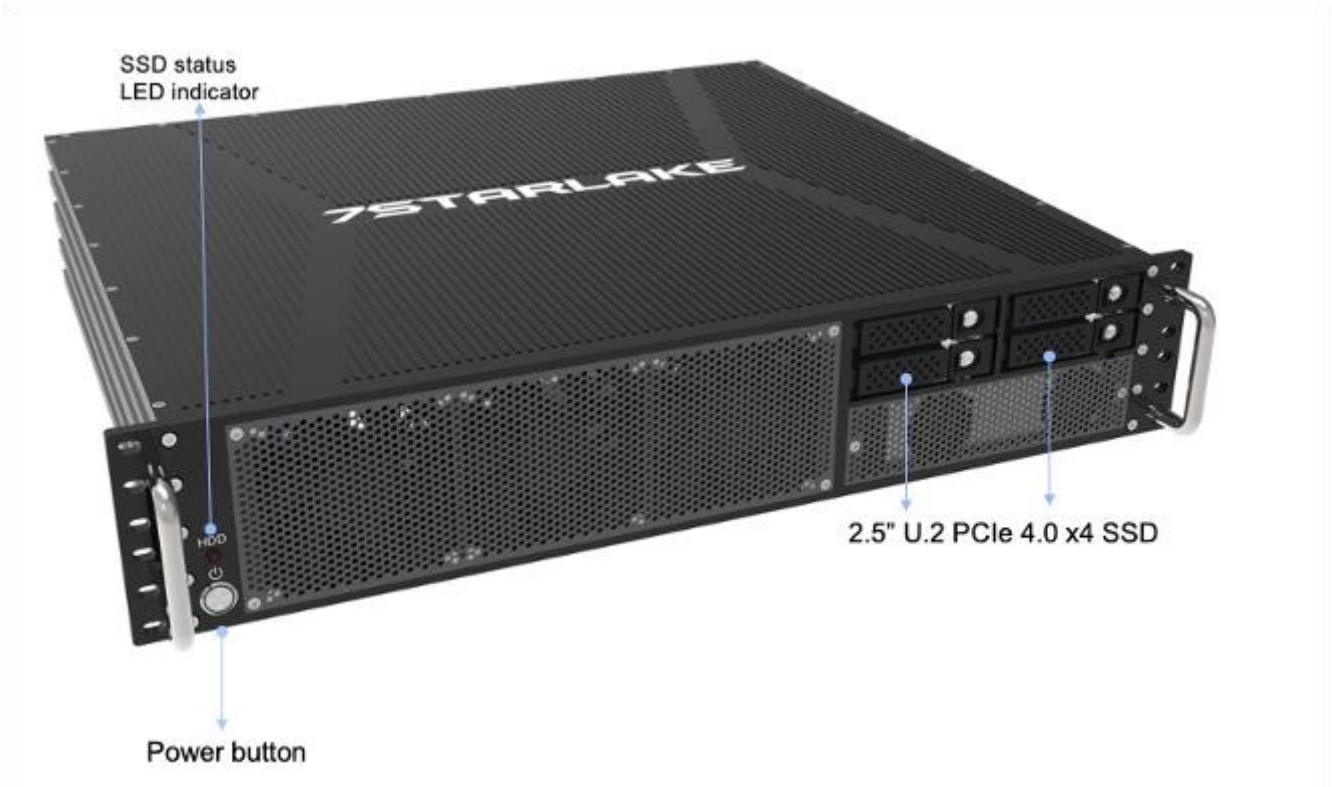
## REAR I/O

IPMI LAN	1
1G LAN	4
10G LAN	2
VGA	1
USB 3.0	4
DC-IN	1

## Environmental

MIL-STD-810 Test	<p>Method 500.5, Procedures I and II (Altitude, Operation): 12,192M, (40,000 ft) for the initial cabin altitude (18.8Kpa or 2.73 Psia)</p> <p>Method 500.5, Procedures III and IV (Altitude, Non-Operation): 15,240, (50,000 ft) for the initial cabin altitude (14.9Kpa or 2.16 Psia)</p> <p>Method 501.5, Procedure I (Storage/High Temperature) Method 501.5, Procedure II (Operation/High Temperature)</p> <p>Method 502.5, Procedure I (Storage/Low Temperature) Method 502.5, Procedure II (Operation/Low Temperature)</p> <p>Method 503.5, Procedure I (Temperature shock) Method 507.5, Procedure II (Temperature &amp; Humidity)</p> <p>Method 509.7 Salt Spray (50±5)g/L</p> <p>Method 514.6, Vibration Category 24/Non-Operating (Category 20 &amp; 24,Vibration) Method 514.6, Vibration Category 20/Operating (Category 20 &amp; 24,Vibration)</p> <p>Method 516.6, Shock-Procedure V Non-Operating (Mechanical Shock) Method 516.6, Shock-Procedure I Operating (Mechanical Shock)</p>
Reliability	<p>No Moving Parts; Passive Cooling.</p> <p>Designed &amp; Manufactured using ISO 9001 Certified Quality Program.</p>
MIL-STD-461	<p>CE102 basic curve, 10kHz - 30 MHz RE102-4, (1.5 MHz) -30 MHz - 5 GHz RS103, 200 MHz - 3.2 GHz, 50 V/m equal for all frequencies EN 61000-4-2: Air discharge: 8 kV, Contact discharge: 6kV EN 61000-4-3: 10V/m EN 61000-4-4: Signal and DC-Net: 1 kV EN 61000-4-5: Leads vs. ground potential 1kV, Signal und DC-Net: 0.5 kV CE and FCC</p>
MIL-STD-1275	<p>Steady State –20V~33V, Surge Low – 18V/500ms, Surge High – 100V/500ms Emitted spikes Injected Voltage surges Emitted voltage surges Voltage ripple (2V) Voltage spikes Starting Operation Reverse polarity</p>
Operating Temp	-20°C to +60°C
Storage Temp.	-40°C to +85°C
Relative Humidity	5% to 95%, non-condensing.

# Appearance



# Dimension

